

COMPAL CONFIDENTIAL

MODEL NAME : AAPA0

PCB NO : LA-C541P

BOM P/N : 4319X031L01

GPIO MAP: Gen7 GPIO Master_0612

MIRAMAR 15"

Skylake H-type (2 chip)

REV : 1.0(A00)

2015.08.17

@,@EMC@ : Nopop Component

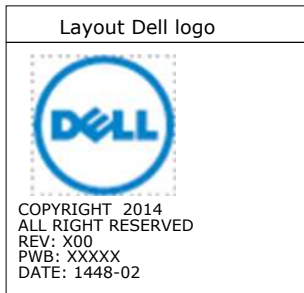
EMC@ : EMI/ESD/RF part

AAC@ : pop AAC config

XDP@ : Total debug Component (pop them until ST)

CONN@ : Connector Component

@AAC@ : Nopop AAC config(control by EC)



PCB 1DI LA-C541P REV0 M/B

Part Number	Description
DAA000A2010	PCB 1DI LA-C541P REV1 M/B

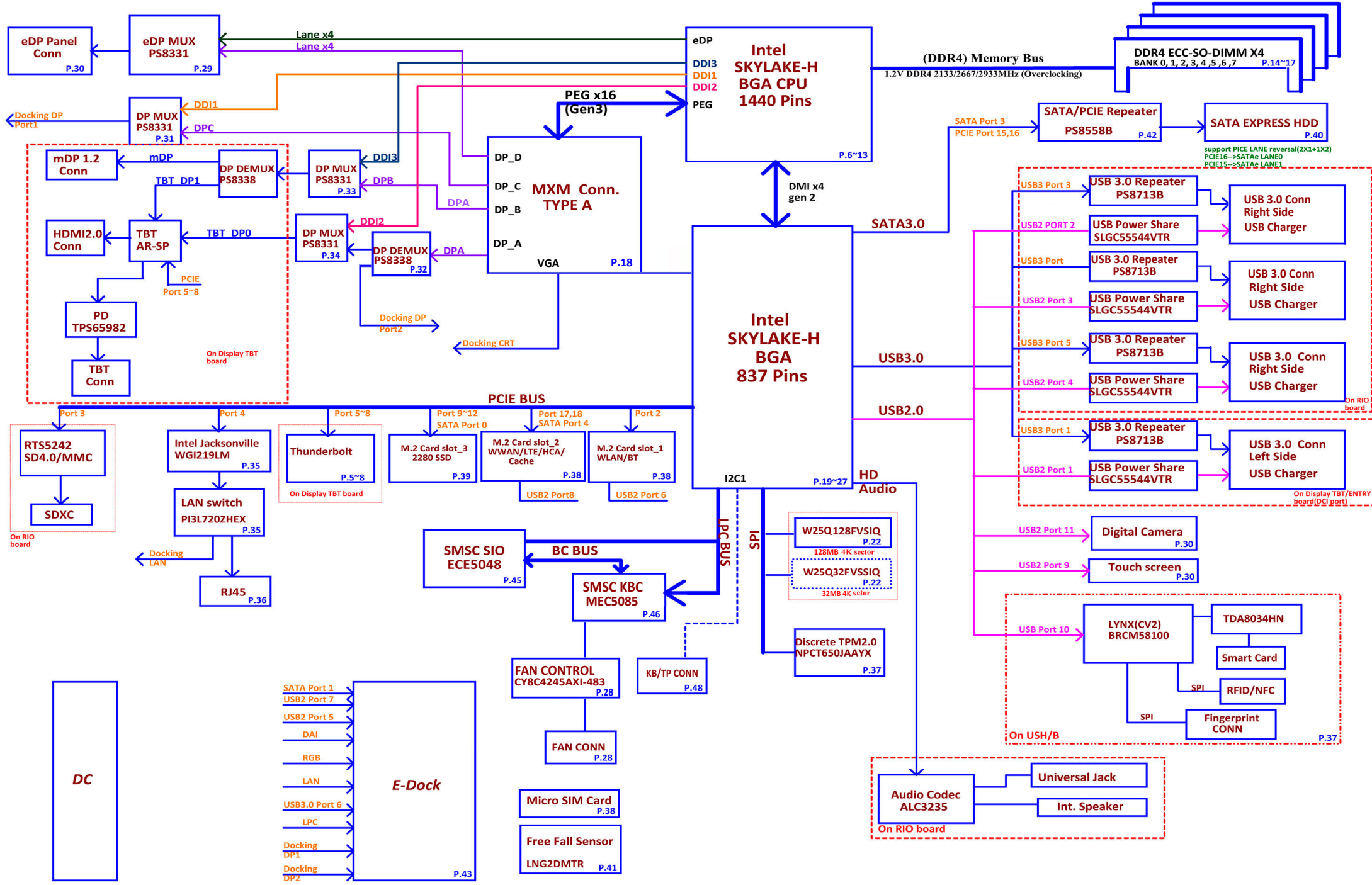
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		Block Diagram	
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POWER STATES

State	Signal	SLP S3#	SLP S4#	SLP S5#	S4 STATE#	SLP M#	ALWAYS PLANE	M PLANE	SUS PLANE	RUN PLANE	CLOCKS
S0 (Full ON) / M0		HIGH	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	ON	ON
S3 (Suspend to RAM) / M1		LOW	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	OFF	OFF
S4 (Suspend to DISK) / M1		LOW	LOW	HIGH	LOW	HIGH	ON	ON	OFF	OFF	OFF
S5 (SOFT OFF) / M1		LOW	LOW	LOW	LOW	HIGH	ON	ON	OFF	OFF	OFF
S3 (Suspend to RAM) / M-OFF		LOW	HIGH	HIGH	HIGH	LOW	ON	OFF	ON	OFF	OFF
S4 (Suspend to DISK) / M-OFF		LOW	LOW	HIGH	LOW	LOW	ON	OFF	OFF	OFF	OFF
S5 (SOFT OFF) / M-OFF		LOW	LOW	LOW	LOW	LOW	ON	OFF	OFF	OFF	OFF

PM TABLE

State	power plane	+3.3V_SUS	+5V_RUN	+3.3V_M	(M-OFF)
	+PWR_SRC +5V_ALW +3.3V_ALW +3.3V_ALW2 +3.3V_ALW_DSW +3.3V_ALW_PCH +3.3V_RTC_LDO +1.8V_ALW +1.0V_PRIM	+1.2V_MEM +2.5V_MEM +1.0V_VCCST	+3.3V_RUN +1.5V_RUN +0.675V_DDR_VTT +3.3V_MXM +5V_MXM +MXM_PWR_SRC		+3.3V_M +VCC_CORE +VCC_EDRAM +VCC_EOPIO +VCC_GTU +VCC_GT +1.0V_VCCSTG +VCC_SA
S0	ON	ON	ON	ON	ON
S3	ON	ON	OFF	ON	OFF
S5 S4/AC	ON	OFF	OFF	ON	OFF
S5 S4/AC don't exist	OFF	OFF	OFF	OFF	OFF

SATA	DESTINATION
SATA 0	SSD 2280
SATA 1	Dock ESATA
SATA 2	NA
SATA 3	SATAe HDD
SATA 4	M.2 Slot-2(cache)
SATA 5	NA

PCH	USB PORT#	DESTINATION
	1	Left Side JUSB1
	2	Right Side JUSB1
	3	Right Side JUSB2
	4	Right Side JUSB3
	5	Docking USB3.0
	6	M.2 Slot-1 (BT)
	7	Docking USB 2.0
	8	M.2 Slot-2 (WWAN/LTE/HCA)
	9	Touch Screen
	10	LYNX(CV2)
	11	Camera
	12	NA
	13	NA
	14	NA

LYNX(CV2)	0	BIO
	1	NA

PCI EXPRESS	DESTINATION
Lane 1	NA
Lane 2	M.2 Slot-1 (WLAN)
Lane 3	MMI(Card reader)
Lane 4	10/100/1G LOM
Lane 5~8	TBT-Alpine Ridge
Lane 9~12	M.2 Slot-3 (SSD 2280)
Lane 13~14	(Dock ESATA),NA(LANE reservsal)
Lane 15~16	SATA-Express HDD(LANE reservsal)
Lane 17~18	M.2 Slot-2 (WWAN/LTE/HCA)

Stack up

Layer No.	Name	Er	Material	Thickness (Material SPEC.) Unit : mil
			SolderMask	IT-158
			Add Plating	
1	Top	3.7	Copper foil	0.5oz
			Prepreg	1080
2	GND/PWR	3.7	Copper foil	1oz
			Core	4mil
3	Sig 1	4.1	Copper foil	1oz
			Prepreg	2116Mx2
4	GND/PWR	3.7	Copper foil	1oz
			Core	4mil
5	Sig 2	3.8	Copper foil	1oz
			Prepreg	1080Hx2
6	Sig 3	3.7	Copper foil	1oz
			Core	4mil
7	GND/PWR	4.1	Copper foil	1oz
			Prepreg	2116Mx2
8	Sig 4	3.7	Copper foil	1oz
			Core	4mil
9	GND/PWR	3.7	Copper foil	1oz
			Prepreg	1080
10	Bottom	3.7	Copper foil	0.5oz
			Add Plating	
			SolderMask	
Overall Thickness (1.45mm ± 10%)				57.09

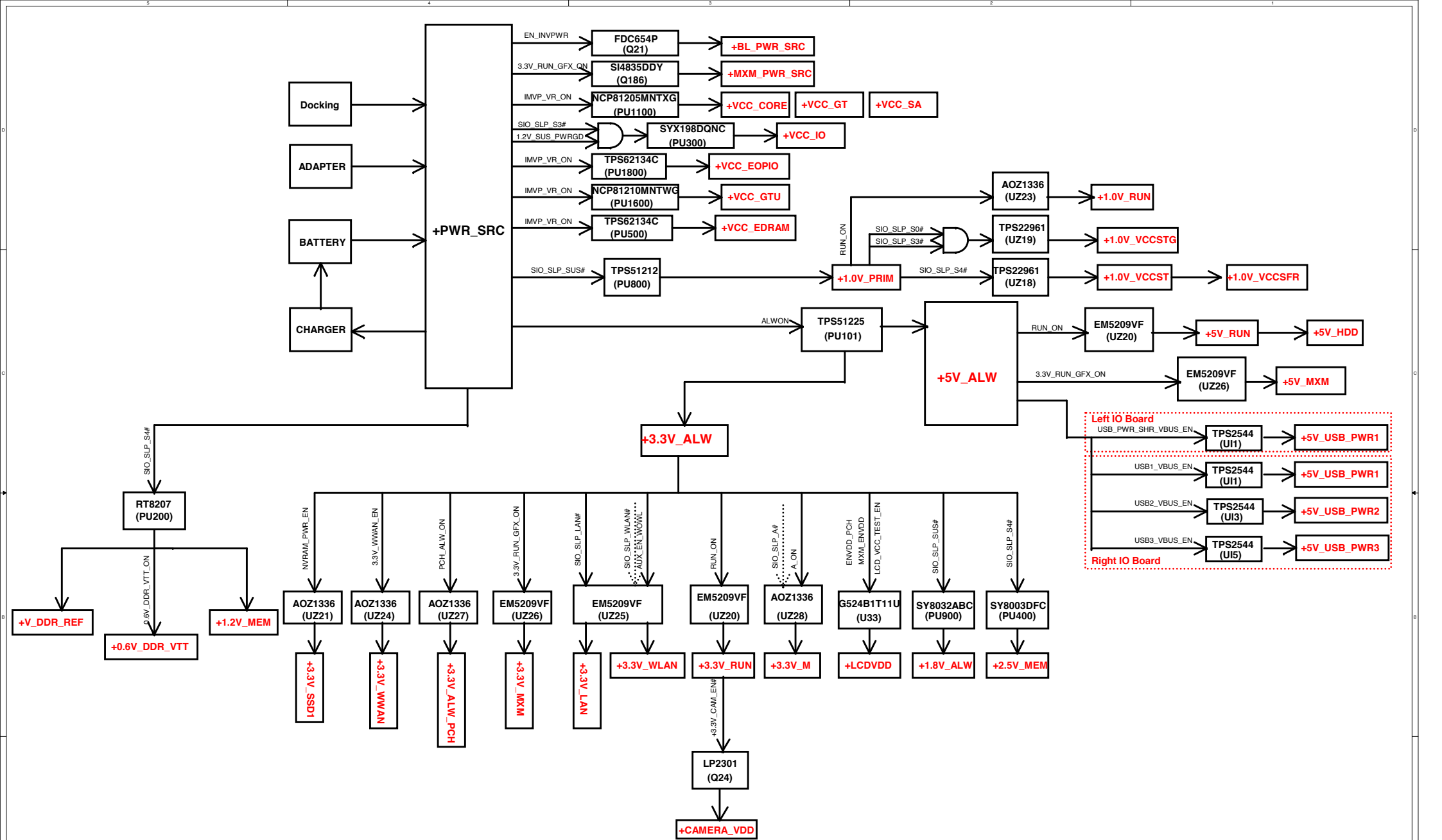
USB3.0	DESTINATION
Port 1	Left Side JUSB1
Port 2	M.2 Slot-2 (WWAN/LTE/HCA)
Port 3	Right Side JUSB1
Port 4	Right Side JUSB2
Port 5	Right Side JUSB3
Port 6	Docking

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Power Rail

LA-C541P

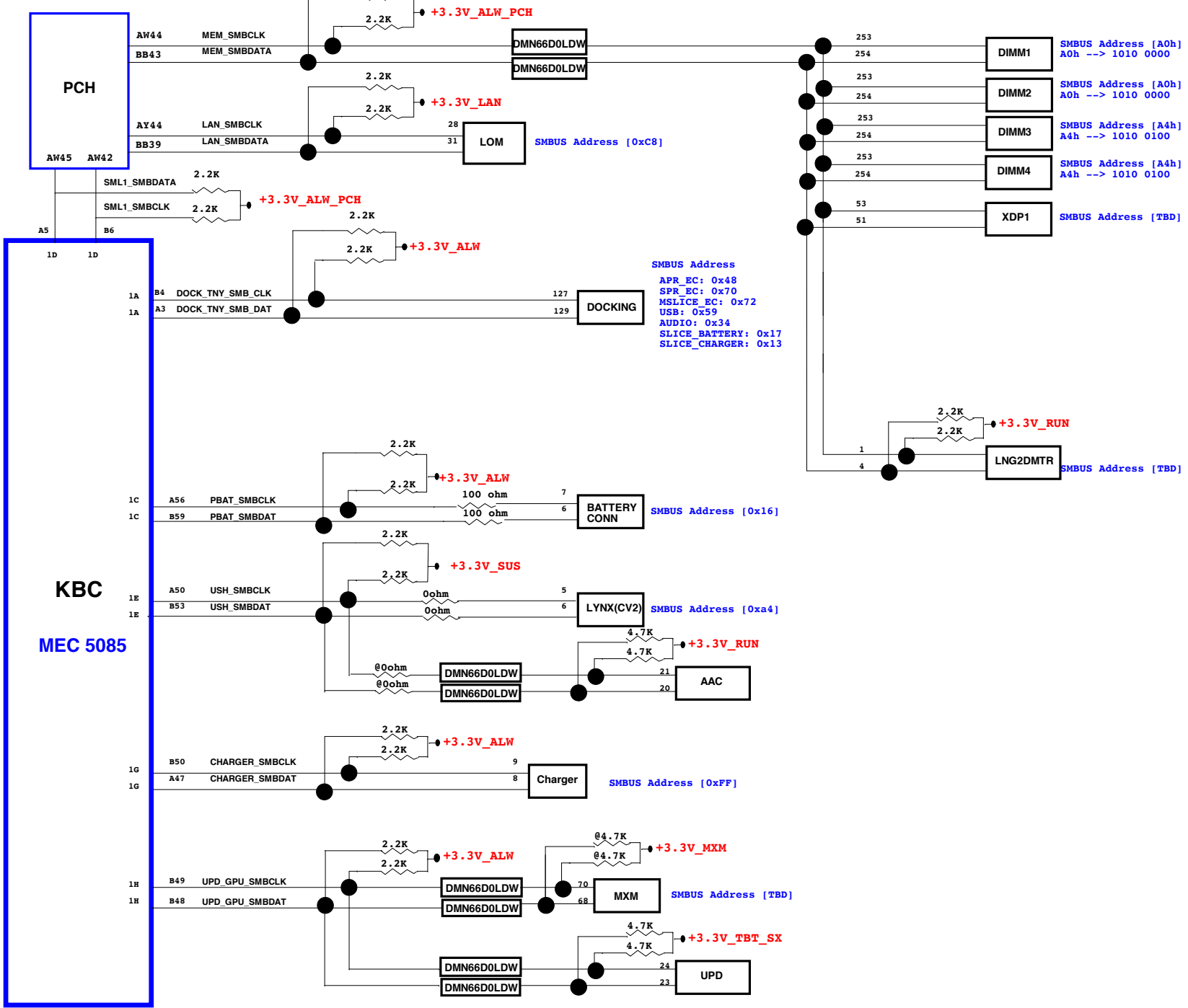
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SMBUS Address [0x9a]



SMBUS Address
 SMB_ADM1032: 0x98
 SMB_DIAG_DUMP: 0x04
 SMB_DIAG_DUMP2: 0x05
 SMB_BLACKTOP: 0x60

KBC
MEC 5085

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